

COPY

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jau-Yuen SU

H/15/D/12/16/02  
Group Art Unit: 3724

Serial No.: 09/394,918

Examiner: O. Flores-Sanchez

Filed: September 13, 1999

Atty. Dkt.: SUJA3001/REF/WKP

For: PROCESS FOR SAWING SUBSTRATE STRIP

Duplicate accepted  
Mail date = 1/25/02AMENDMENT AND RESPONSECommissioner for Patents  
Washington, D.C. 20231Stephen Marcus  
Special Program Examiner  
Group 3700

Sir:

This is responsive to the Office Action mailed October 25, 2001 (Paper No. 12) in the above application. Reconsideration of the application is respectfully requested in view of the following amendments and remarks.

AMENDMENT

Please amend this application as follows:

IN THE CLAIMS

Please amend claim 9 as follows (an APPENDIX OF MARKED-UP AMENDED CLAIM is attached):

—9. (Twice Amended) The process as claimed in Claim 7, further comprising the step of cutting the substrate strip according to cutting tracks defined by the cutting marks parallel to the longitudinal axis.